

Claims

1. A semiconductor device comprising:

5 a semiconductor element, having a primary surface and a back surface, said semiconductor element having an element electrode on the primary surface; and

a circuit board having a primary surface and a back surface, said circuit board having a board electrode on at least the back surface, said circuit board having a predetermined opening hole formed therein;

10 wherein the primary surface of said semiconductor element is bonded to the primary surface of said circuit board by means of an adhesive layer which is greater in size than the primary surface of said semiconductor element, and said element electrode of said semiconductor element is connected to said board electrode provided
15 on the back surface of said circuit board via said opening hole.

20 2. The semiconductor device as according to claim 1, wherein the surrounding regions of the side surfaces of said semiconductor element on said circuit board are sealed with resin so as to assume a flange structure.

25 3. The semiconductor device as according to claim 1, wherein the surrounding regions of the side surfaces and back surface of said semiconductor element are sealed with resin.

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